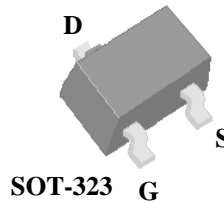




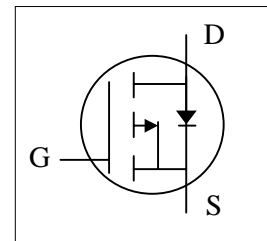
- ▼ Simple Gate Drive
- ▼ Small Package Outline
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free



BV_{DSS}	-20V
$R_{DS(ON)}$	800mΩ
I_D	-550mA

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current ³	-550	mA
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current ³	-440	mA
I_{DM}	Pulsed Drain Current ¹	-2.5	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation	0.35	W
	Linear Derating Factor	0.003	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient ³	360	°C/W



Electrical Characteristics @T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-20	-	-	V
ΔBV _{DSS} /ΔT _j	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D =-1mA	-	-0.01	-	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-550mA	-	-	600	mΩ
		V _{GS} =-4.5V, I _D =-500mA	-	-	800	mΩ
		V _{GS} =-2.5V, I _D =-300mA	-	-	1000	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	-0.5	-	-1.2	V
g _{fs}	Forward Transconductance	V _{DS} =-5V, I _D =-500mA	-	1	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-20V, V _{GS} =0V	-	-	-1	uA
	Drain-Source Leakage Current (T _j =70°C)	V _{DS} =-16V, V _{GS} =0V	-	-	-10	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±12V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge ²	I _D =-500mA	-	1.7	2.7	nC
Q _{gs}	Gate-Source Charge	V _{DS} =-16V	-	0.3	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =-4.5V	-	0.4	-	nC
t _{d(on)}	Turn-on Delay Time ²	V _{DS} =-10V	-	5	-	ns
t _r	Rise Time	I _D =-500mA	-	8	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω, V _{GS} =-5V	-	10	-	ns
t _f	Fall Time	R _D =20Ω	-	2	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	66	105.6	pF
C _{oss}	Output Capacitance	V _{DS} =-10V	-	25	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	20	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{SD}	Forward On Voltage ²	I _S =-300mA, V _{GS} =0V	-	-	-1.2	V

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on FR4 board, t ≤ 10 sec.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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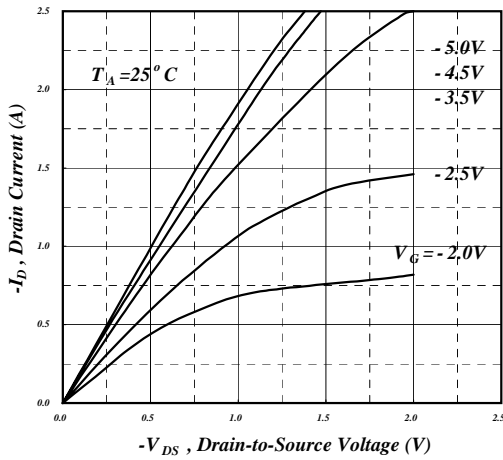


Fig 1. Typical Output Characteristics

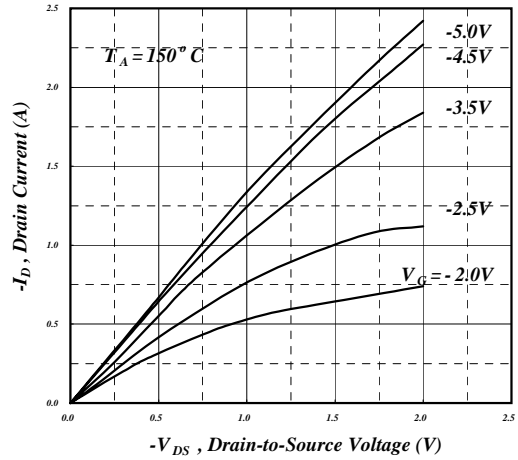


Fig 2. Typical Output Characteristics

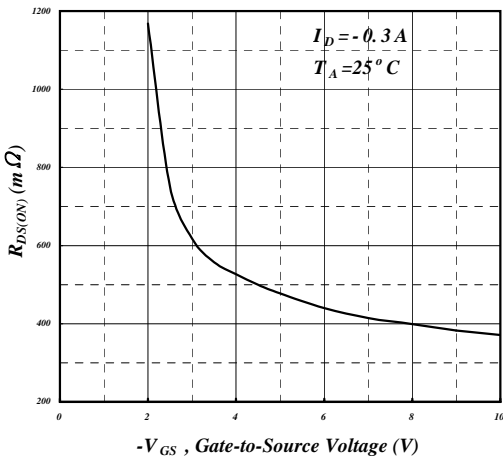


Fig 3. On-Resistance v.s. Gate Voltage

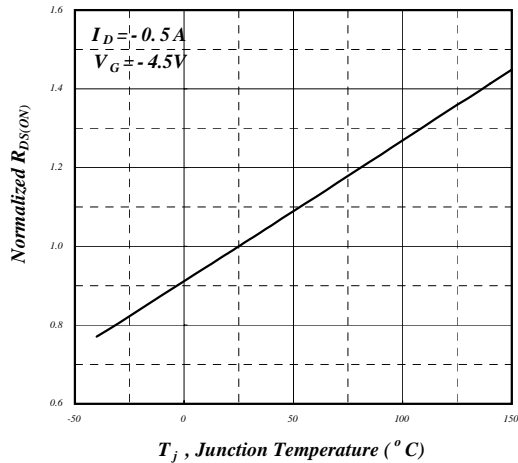


Fig 4. Normalized On-Resistance v.s. Junction Temperature

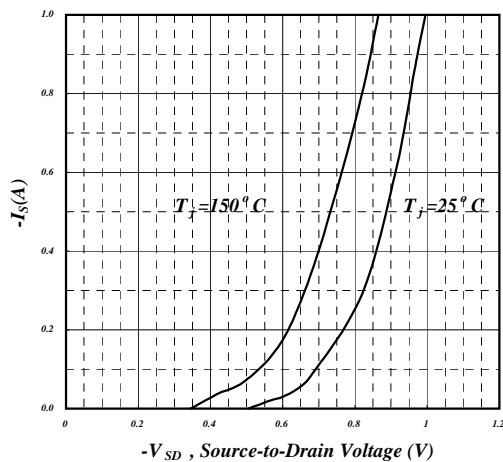


Fig 5. Forward Characteristic of Reverse Diode

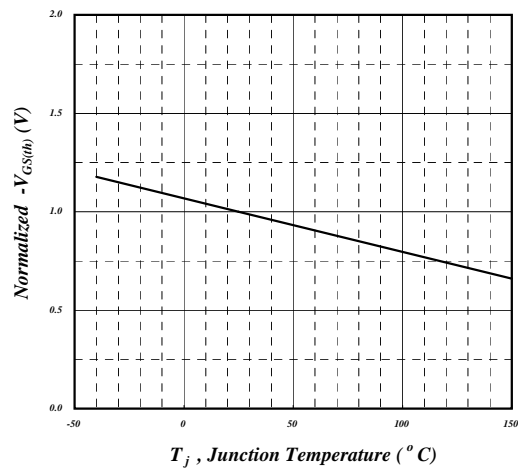


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



AP1333GU-HF

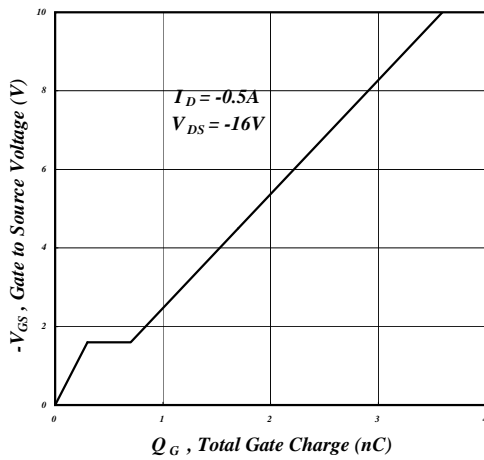


Fig 7. Gate Charge Characteristics

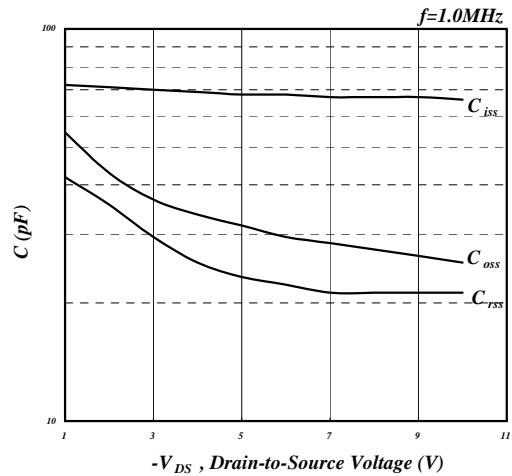


Fig 8. Typical Capacitance Characteristics

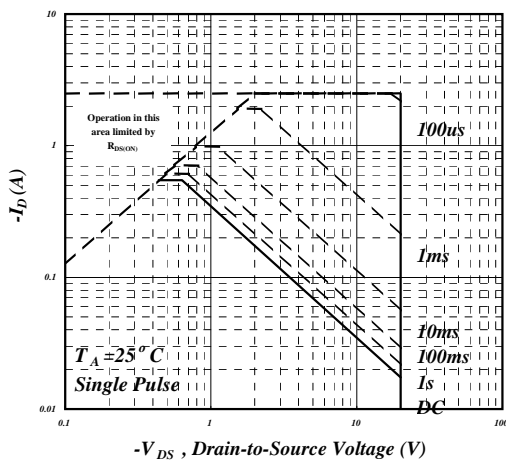


Fig 9. Maximum Safe Operating Area

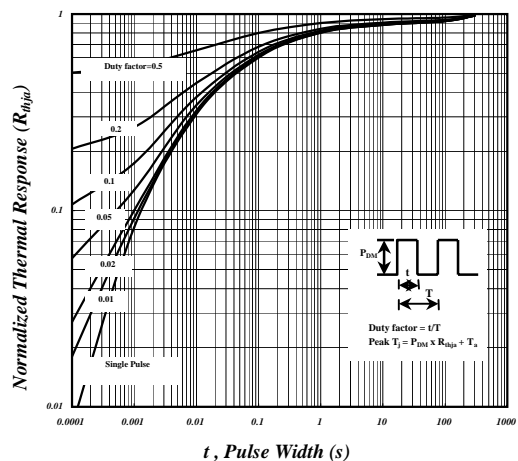


Fig 10. Effective Transient Thermal Impedance

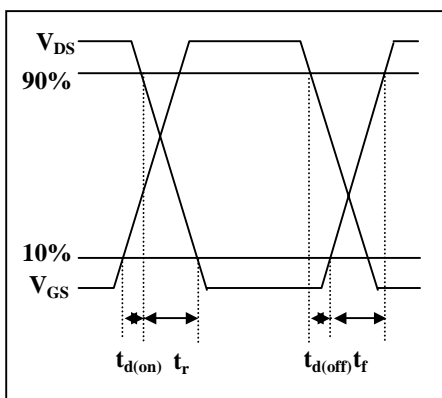


Fig 11. Switching Time Waveform

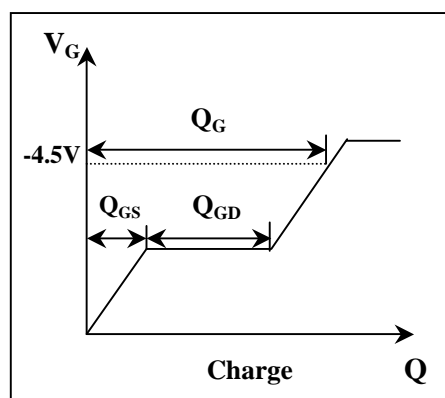


Fig 12. Gate Charge Waveform